



# SOT1092-1

plastic thermal enhanced very thin quad flat package; no leads; 36 terminals; body 6 x 6 x 0.85 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HVQFN36
<b>Package type industry code</b>	HVQFN36
<b>Package style descriptive code</b>	HVQFN (thermal enhanced very thin quad flatpack; no leads)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-220
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	12-11-2008

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	5.9	-	6	6.1	mm
E	package width	5.9	-	6	6.1	mm
A	seated height	0.8	-	0.85	0.9	mm
A <sub>2</sub>	package height	0.6	-	0.65	0.7	mm
n <sub>2</sub>	actual quantity of termination	-	-	36	-	

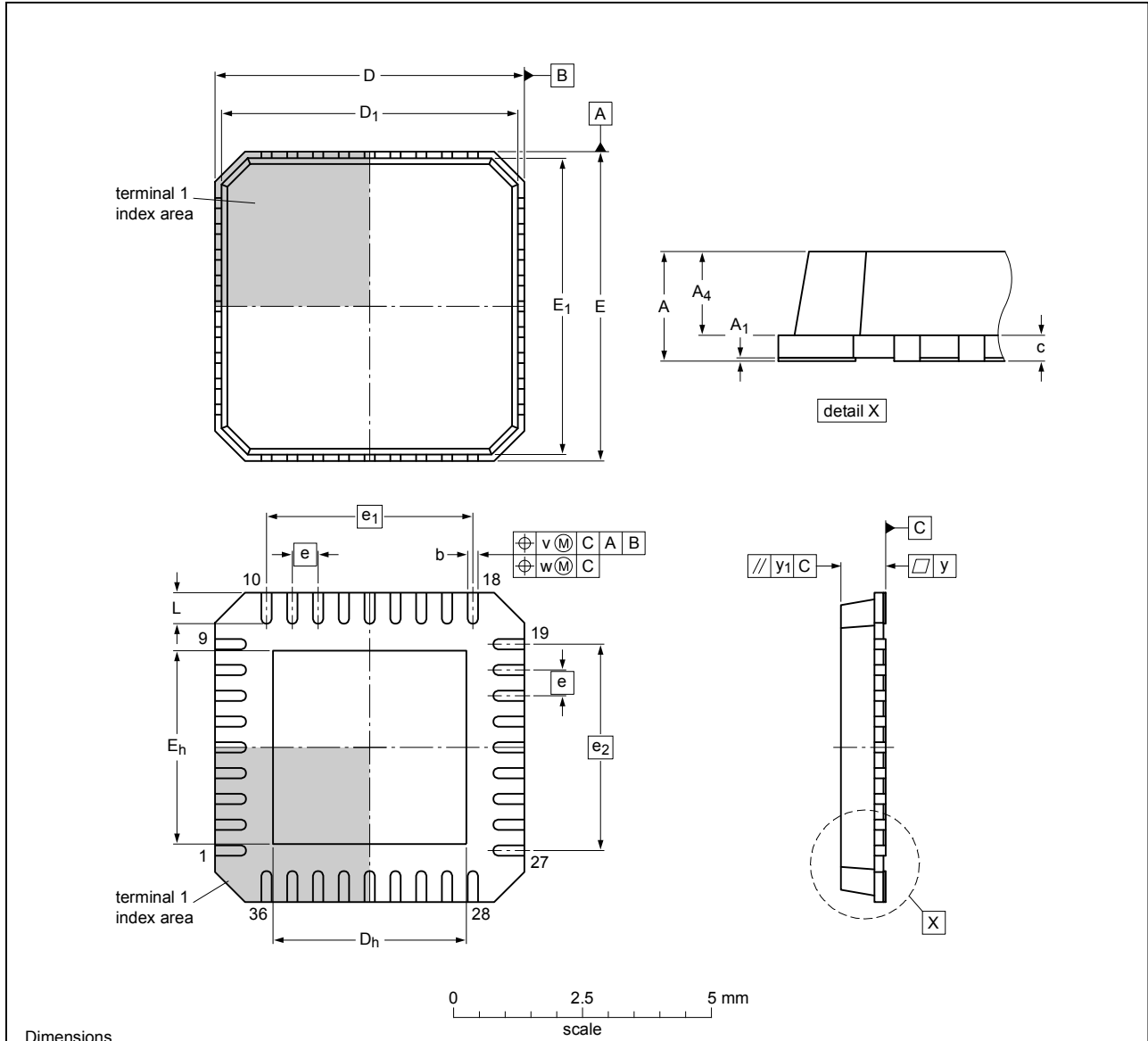


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## 2. Package outline

HVQFN36: plastic thermal enhanced very thin quad flat package; no leads; 36 terminals; body 6 x 6 x 0.85 mm

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Dimensions

Unit	A <sup>(1)</sup>	A <sub>1</sub>	A <sub>4</sub>	b	c	D <sup>(1)</sup>	D <sub>1</sub>	D <sub>h</sub>	E <sup>(1)</sup>	E <sub>1</sub>	E <sub>h</sub>	e	e <sub>1</sub>	e <sub>2</sub>	L	v	w	y	y <sub>1</sub>
mm	max 0.90	0.05	0.70	0.30		6.1	5.85	3.85	6.1	5.85	3.85				0.75				
	nom 0.85	0.01	0.65	0.23	0.2	6.0	5.75	3.70	6.0	5.75	3.70	0.5	4	4	0.60	0.1	0.05	0.05	0.1
	min 0.80	0.00	0.60	0.18		5.9	5.65	3.55	5.9	5.65	3.55				0.50				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1092-1	---	MO-220	---		08-11-12

Fig. 1. Package outline HVQFN36 (SOT1092-1)

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### 3. Legal information

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